



[WeD2] Material & Process

Session Date	November 12 (Wed.), 2025
Session Time	14:10-15:50
Session Room	Room D (Sydney Room, 2F)
Session Chair	Prof. Su-Mi Hur (Chonnam Nat'l Univ., Korea)

[WeD2-1] [Invited]

14:10-14:40

Advanced Patterning: Tackling the Big Problems in Printing Small Features

Ben Eynon (Lam Research, USA)

[WeD2-2] [Invited]

14:40-15:10

Overview of Innovative Lithography Patterning Process Materials Contributing to Next Wave of Challenge on Semiconductor Architecture

Ethan C B Lee, Seoung-Woo Jang, Sang-Hee Park, Byeri Yoon (Samsung SDI, Korea)

[WeD2-3] [Invited]

15:10-15:30

EUV vs. E-Beam Photoresists: Cross-Platform Analysis and Optimization Strategies

Hyungkun Lee, Jaehyun Kim, Myounghyun Hur, Jeongwoo Kim, and Jeongsik Kim (Dongjin Semichem Co., Ltd., Korea)

[WeD2-4] [Invited]

15:30-15:50

EUV Mask Local CD Correction System Development via Laser Irradiation

Hyun Yoon, Yujin Cho, Ki Hoon Choi, Hojong Hwang, Seung Eon Oh, Seryeyohan Cho, Jin Yeong Sung, Jangjin Lee, Taeshin Kim, Sang Hyeon Ryu, Youngho Park, Donggeun Lee, Joon Ho Won (SEMES, Korea), Yong Woo Kim, Jong Keun Oh, Jong Ju Park (Samsung Electronics Co., Ltd., Korea), and Byeonggeun Kim (SEMES, Korea)